

March 17, 2003

MEMORANDUM

TO: District Structures Design Engineers:
Gerry Moiliere, Rod Nelson, Keith Shores, John Danielsen, Neil Kenis, Kim Saing, Jose Rodriguez, and Agnes Spielmann
District Construction Engineers:
Jon Sands, Henry Haggerty, Steve Benak, Jennifer Olson, Frank O-Dea, Mark Croft, James Moulton, and Bill Sears

FROM: William N. Nickas, P.E., State Structures Design Engineer, and Ananth Prasad, P.E., State Construction Engineer

COPIES: Duane F. Brautigam, Steve Plotkin, William Domico, Robert Nichols, Jack Evans, and Area Structures Engineers

SUBJECT: **Construction Memorandum Number 10-03**
SDO Temporary Design Bulletin No. CO-03-01

By receipt of this memorandum, discontinue requiring QPL products complying with Specification Section 937, Adhesive Bonding Material Systems for Structural Applications, for pile splice applications. In lieu thereof, and until further notification, permit pile splices to be constructed using QPL products that comply with Specification Section 926, Epoxy Compounds, Type B.

Despite continued efforts to develop QPL-approved Adhesive Bonding Material Systems for pile splice applications, the low sag and quick-set characteristics of all current QPL products does not permit enough set time to construct pile splices under typical field conditions.

In the interim, design documents, standard drawings, and specification requirements will be modified as described above and will be incorporated in the contract documents for all FDOT projects let after January 1, 2004. Additionally, laboratory testing of the current QPL products meeting Section 926 for Type B Epoxy is being proposed to establish QPL acceptance criteria for pile splice applications. Testing probably will include straight tension pullout tests of dowels as well as full-scale flexural testing of typical pile splices.

WNN/AP:h